ISS brings full turn-key testing from semiconductor product qualifications, reliability, failure analysis and any related technical services. ISS's vast experienced engineering staff is capable of handling all challenges from the device to system level.

Integrated Semiconductor Solutions is committed to providing distinguished services by offering High Quality, Competitive Pricing and Short Lead Time. We work with our customers in saving cost, resources and time. Our goal is to Make Testing EaZy.

**BURN-IN & PRODUCT RELIABILITY**
- Static and Dynamic HTOL
- Intelligent life test (during Burn-in)
- Adaptation with common ovens: MCC, Criteria, Aehr, Adeco... etc
- Production Burn-in

**ESD & LU TESTING**
- Human Body Model (HBM)
- Machine Model (MM)
- Charged Device Model (CDM)
- Latch-up

**FAILURE ANALYSIS**
- Die pull, ball shear, wire bond pull
- Solderability, SEM/EDS
- Materials analysis: TMA, TGA, DMA, DSC, FT-IR, Dielectric Breakdown, HiPot, Arc Resistance, CTI, Permittivity, Impact Testing
- Optical Inspection (2000x), CSAM, X-ray and Curve Trace
- Decapsulation & Cross Section

**ATE TESTING**
- Test Solutions (FT and Wafer Probe)
- Test programs for ESD/LU, Package qual and device HTOL
- Product characterization and pre-production ramp up support

**PACKAGE QUALIFICATIONS**
- Preconditioning (level 1-4)
- Convection Reflow, N2 shielding
- Biased/Unbiased & 85/85
- MSL (Level 1-4)
- Temperature Cycling
- HTS and Bake
- C-Sam

**TEST HARDWARE AND MANUFACTURING**
- Burn-in HAST and Custom HW Design
- PCB, assembly and manufacturing
- DUT boards for various ATE Platforms
- Teradyne, Advantest, Chroma... etc

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Office: (714) 505-0970
Integrated Semiconductor Solutions Inc (ISS) is based in Southern California. Our core focus is to provide customers with semiconductor IC testing services they need. ISS brings full turn-key testing for semiconductor product qualification, reliability, failure analysis and any related technical services. ISS’s experienced engineering staff is capable of handling all challenges from the device to system level.

ISS LABS: QUALITY, SERVICE, EXPERIENCE
ISS offers semiconductor test solutions that caters to each phase of product development with broad range of testing and reliability services, eliminating the need for multiple vendors. We offer proactive services which address the compressed time constraint for product qualification and to reduce the time to market, ISS is shaped by skilled technical teams capable of providing the foundation for excellent customer support, at ISS we believe in long term partnership with customers. We put our expertise at customer disposition with the intentions to deliver highest standards of services.

OUR OBJECTIVES
ISS Lab delivers a significant market advantage to customers in the breadth of our services and solutions, ISS’s competitive edges are gained from equipment investment and our high level in-house engineering expertise. We provide an efficient solution that consistently result in major cost reductions and critical time savings. Offering much more than performing the services, ISS on-site technical staff can debug, verify and validate test results and help customers quickly identify and solve product qualification issues. ISS Lab’s distinctive, dynamic team has repeatedly achieved a high and first-time success rate.

PACKAGE QUALIFICATIONS
- Temperature Humidity Bias
- Preconditioning, Moisture Absorption (level 1 to 4) 1/8 Rev
- High Temperature Bake, Solderability
- HAST, biased and unbiased 85/85
- Temperature Cycling
- HTS and Bake, C-Sam

BURN-IN & PRODUCT RELIABILITY
- Static and Dynamic HTOL
- Intelligent life test (during Burn-in)
- Adaptation with common ovens: MCC, Criteria, Aesir MAX-3, Adec, etc
- Production Burn-in

TEST HARDWARE AND MANUFACTURING
- Burn-in HAST and Custom HW Design
- PCB, assembly and manufacturing
- DUT boards for various ATE platforms: Teradyne, Advantest, etc

ESD & LU TESTING
- Human Body Model (HBM)
- Machine Model (MM)
- Charged Device Model (CDM)
- Latchup

FAILURE ANALYSIS
- Die pull, ball shear, wire bond pull
- Solderability, SEM/EDS
- Materials analysis: TMA, TGA, DTA, DSC, FTR, Dielectric Breakdown, HiPol, Arc, Resistance, CTI, Permittivity, Impact Testing
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